



Material Content Data Sheet



Sales Product Name	TLE7238SL			Issued		28. August 2013		
MA#	MA000982080							
Package	PG-SSOP-24-5			Weight*		147.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.437	5.04	5.04	50432	50432
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		422	
	non noble metal	iron	7439-89-6	1.245	0.84		8445	
	non noble metal	copper	7440-50-8	50.568	34.29	35.18	342900	351873
wire	noble metal	gold	7440-57-5	0.589	0.40	0.40	3997	3997
encapsulation	organic material	carbon black	1333-86-4	0.166	0.11		1126	
	plastics	epoxy resin	-	7.642	5.18		51817	
	inorganic material	silicondioxide	60676-86-0	75.253	51.04	56.33	510287	563230
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11391	11391
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2477	2477
glue	plastics	acrylic resin	-	0.539	0.37		3652	
	noble metal	silver	7440-22-4	1.909	1.29	1.66	12948	16600
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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